

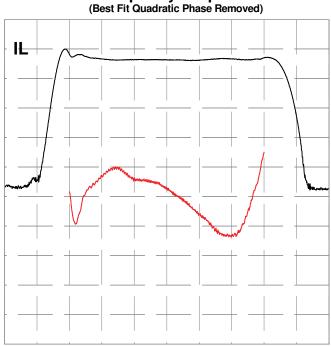
Specifications

| Parameter | Symbol | Min | Typical | Max | Unit |
|-----------------------------------|----------------|------|---------|-------|--------|
| Center Frequency | F ₀ | | 60 | | MHz |
| Bandwidth | В | | 6 | | MHz |
| Dispersion | Т | | 50 | | µsec |
| Delay | To | 28.4 | 28.776 | 29.1 | µsec |
| Insertion Loss | IL | | 46.7 | 48 | dB |
| Slope | S ₀ | 8.28 | 8.36 | 8.37 | µs/MHz |
| Pulse Width at -3 dB | | | 0.14 | 0.142 | µsec |
| Sidelobes for $ t - T_0 < T$ | | | -11.9 | -11 | dB |
| Time Spurious for $ t - T_0 > T$ | | | -62 | -60 | dB |
| Substrate Material | STQ | | | | |

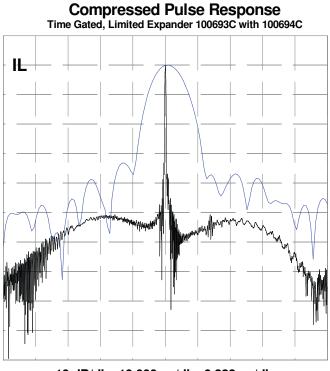
Notes

- 1. Center Frequency (F_0) and Bandwidth (B) are defined, not measured. Dispersion (T) is defined as $|B * S_0|$.
- 2. Insertion Loss is the minimum loss for $|f F_0| < .5B$
- 3. Delay and Slope determined by best fit quadratic pulse in $|f F_0| < .5B$.
- 4. Specifications are at 22 °C only. Unit will operate undamaged from -54 °C to 125 °C with shifts dF₀ = $-x * F_0$, dT₀ = $x * (T_0 + S_0 * F_0)$, dS₀ = $x * 2 * S_0$, where $x = 3E-8 * (temperature - 22 °C)^2$

Typical Performance



10 dB/div, 10 deg/div, 0.900 MHz/div



10 dB/div, 10.000 us/div, 0.333 us/div

Frequency Response Best Eit Quadratic Phase Bemoved)

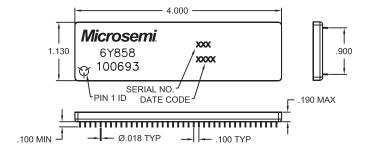


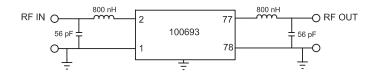
100693C

RD60-6-50U+ 60 MHz Dispersive Delay Line 6 MHz Bandwidth

Package Outline

Matching







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